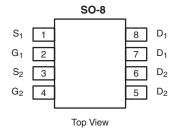




Dual N-Channel 20 V MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
20	0.0046 at V _{GS} = 10 V	19.8 ^a	14.5		
	0.006 at V _{GS} = 4.5 V	17.3 ^a			



Ordering Information: Si4204DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

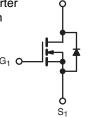
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

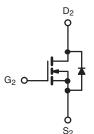


COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converter
- Fixed Telecom
- Notebook PC





N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A =$	= 25 °C, unless other	wise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	20	V		
Gate-Source Voltage	V_{GS}	± 20]		
	T _C = 25 °C		19.8		
Continuous Drain Current /T 150 °C)	T _C = 70 °C	,	15.9		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	15.5 ^{b, c}		
	T _A = 70 °C		12.2 ^{b, c}		
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	50		
Course Drain Current Diada Current	T _C = 25 °C		2.7	Α	
Source-Drain Current Diode Current	T _A = 25 °C	I _S	1.6 ^{b, c}		
Pulsed Source-Drain Current	I _{SM}	50			
Single Pulse Avalanche Current		I _{AS} 20			
L = 0.1 mH		E _{AS}	20	1	
	T _C = 25 °C		3.25		
Maximum Daylar Dissination	T _C = 70 °C	Б	2.10	W	
Maximum Power Dissipation	T _A = 25 °C	P_{D}	2.0 ^{b, c}		
	T _A = 70 °C		1.25 ^{b, c}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Тур.	Max.	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	45	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady-State	R _{thJF}	29	38	0/ / /		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 120 °C/W.

Si4204DY

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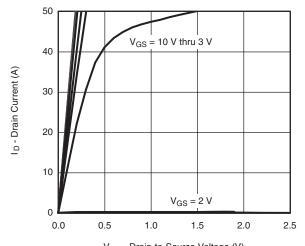
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	<u> </u>						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		20			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.8		mV/°C	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			100	nA	
7. 0. 1/1. 5. 0	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1 .		
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	20			Α	
Ducin Course On Chata Basistanash		V _{GS} = 10 V, I _D = 10 A		0.0038	0.0046	Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 8 A		0.0047	0.0060		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 10 A		50		S	
Dynamic ^a							
Input Capacitance	C _{iss}			2110			
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ MHz}$		926		pF	
Reverse Transfer Capacitance	C _{rss}] [235			
Total Cata Charms	Qg	V _{DS} = 10 V, V _{GS} = 10 V, I _D = 10 A		30	45		
Total Gate Charge				14.5	22	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		4.5			
Gate-Drain Charge	Q_{gd}			3.9			
Gate Resistance	R_g	f = 1 MHz	0.4	1.4	2.8	Ω	
Turn-On Delay Time	t _{d(on)}			8	16		
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_L = 1 \Omega$		15	30		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		24	45		
Fall Time	t _f			9	18	ne	
Turn-On Delay Time	t _{d(on)}			18	35	ns	
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_L = 1 \Omega$		24	45		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		26	50		
Fall Time	t _f			13	26		
Drain-Source Body Diode Characterist	cs						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.7	Α	
Pulse Diode Forward Current ^a	I _{SM}				50	^	
Body Diode Voltage	V_{SD}	I _S = 3 A		0.70	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			20	40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	N-Channel		10	20	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A, dI/dt} = 100 \text{ A/µs, T}_J = 25 ^{\circ}\text{C}$		11		nS	
Reverse Recovery Rise Time	t _b]		9			

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

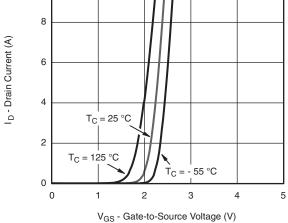




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

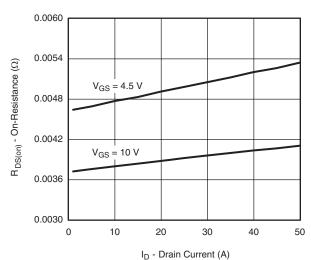


 V_{DS} - Drain-to-Source Voltage (V) **Output Characteristics**

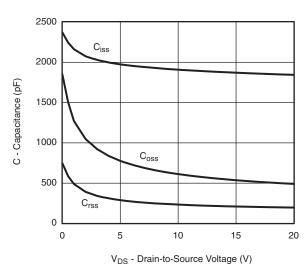


10

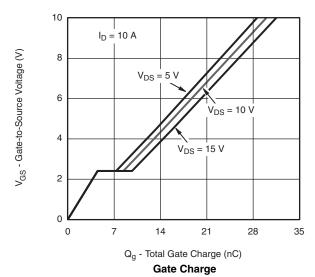
Transfer Characteristics

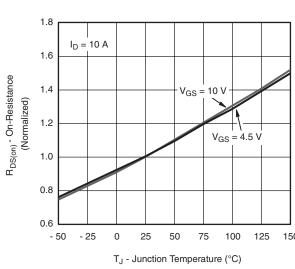


On-Resistance vs. Drain Current and Gate Voltage



Capacitance

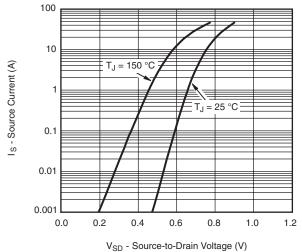




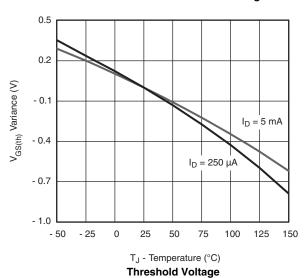
On-Resistance vs. Junction Temperature

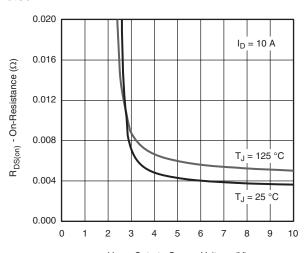
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



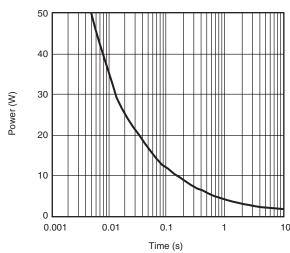
Source-Drain Diode Forward Voltage



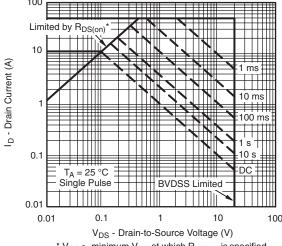


V_{GS} - Gate-to-Source Voltage (V)





Single Pulse Power, Junction-to-Ambient

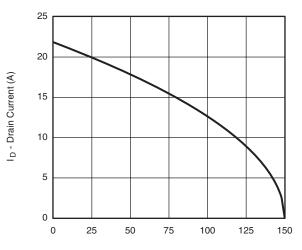


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

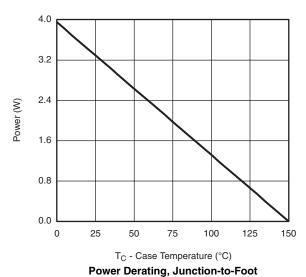


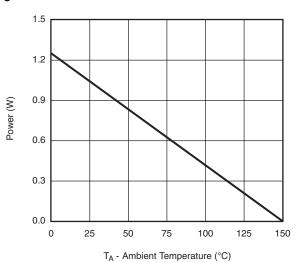
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 T_C - Case Temperature (°C)

Current Derating*





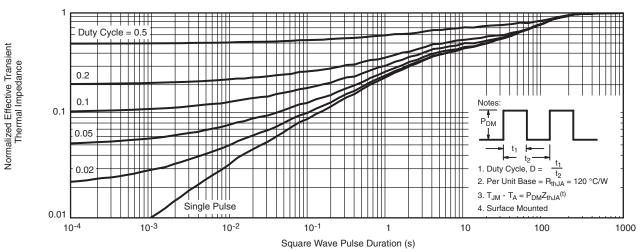
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

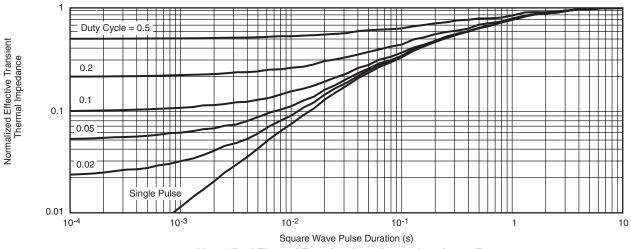
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS INCHES			HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

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